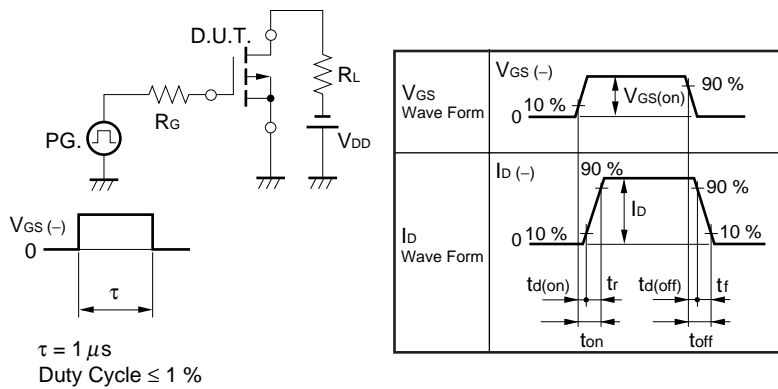


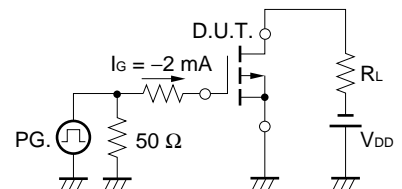
ELECTRICAL CHARACTERISTICS (TA = 25 °C, All terminals are connected.)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	R _{DS(on)1}	V _{GS} = -10 V, I _D = -3 A		26	33	mΩ
	R _{DS(on)2}	V _{GS} = -4.5 V, I _D = -3 A		44	59	mΩ
Gate to Source Cut-off Voltage	V _{GS(off)}	V _{DS} = -10 V, I _D = -1 mA	-1.5	-2.0	-2.5	V
Forward Transfer Admittance	y _{fs}	V _{DS} = -10 V, I _D = -3 A	3.0	7.5		S
Drain Leakage Current	I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V			-1	μA
Gate to Source Leakage Current	I _{GSS}	V _{GS} = ± 25 V, V _{DS} = 0 V			± 10	μA
Input Capacitance	C _{iss}	V _{DS} = -10 V		830		pF
Output Capacitance	C _{oss}	V _{GS} = 0 V		330		pF
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		130		pF
Turn-on Delay Time	t _{d(on)}	I _D = -3 A		15		ns
Rise Time	t _r	V _{GS(on)} = -10 V		120		ns
Turn-off Delay Time	t _{d(off)}	V _{DD} = -15 V		70		ns
Fall Time	t _f	R _G = 6 Ω		50		ns
Total Gate Charge	Q _G	I _D = -6 A		15		nC
Gate to Source Charge	Q _{GS}	V _{DD} = -24 V		3		nC
Gate to Drain Charge	Q _{GD}	V _{GS} = -10 V		5		nC
Body Diode Forward Voltage	V _{F(S-D)}	I _F = 6 A, V _{GS} = 0 V		0.82		V
Reverse Recovery Time	t _{rr}	I _F = 6 A, V _{GS} = 0 V		35		ns
Reverse Recovery Charge	Q _{rr}	di/dt = 100 A / μs		15		nC

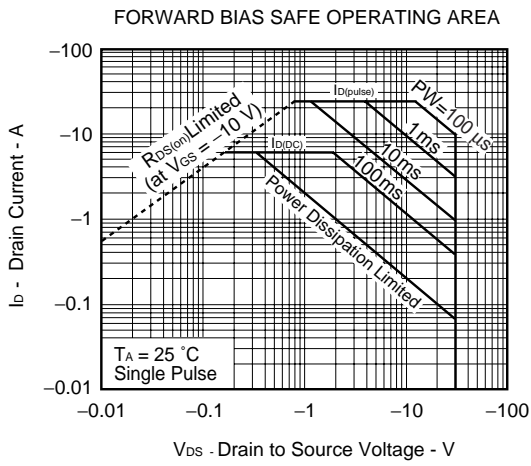
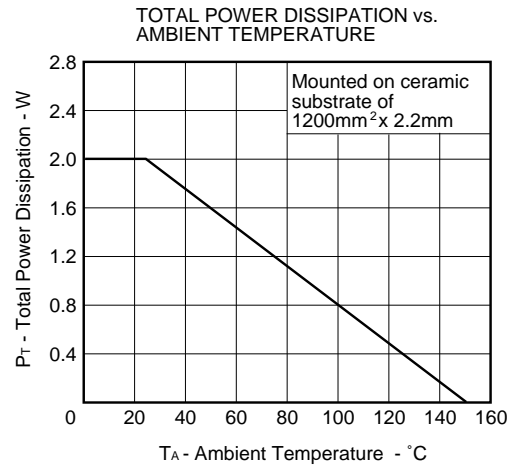
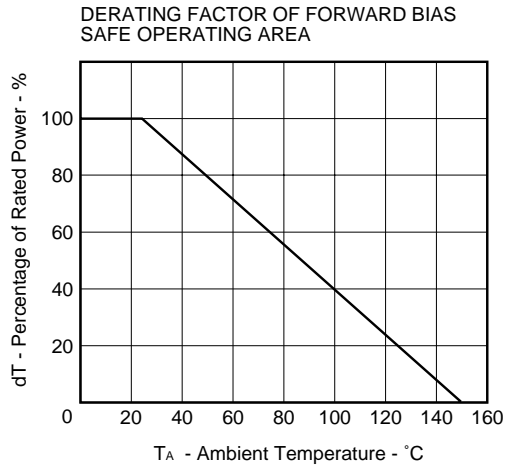
TEST CIRCUIT 1 SWITCHING TIME



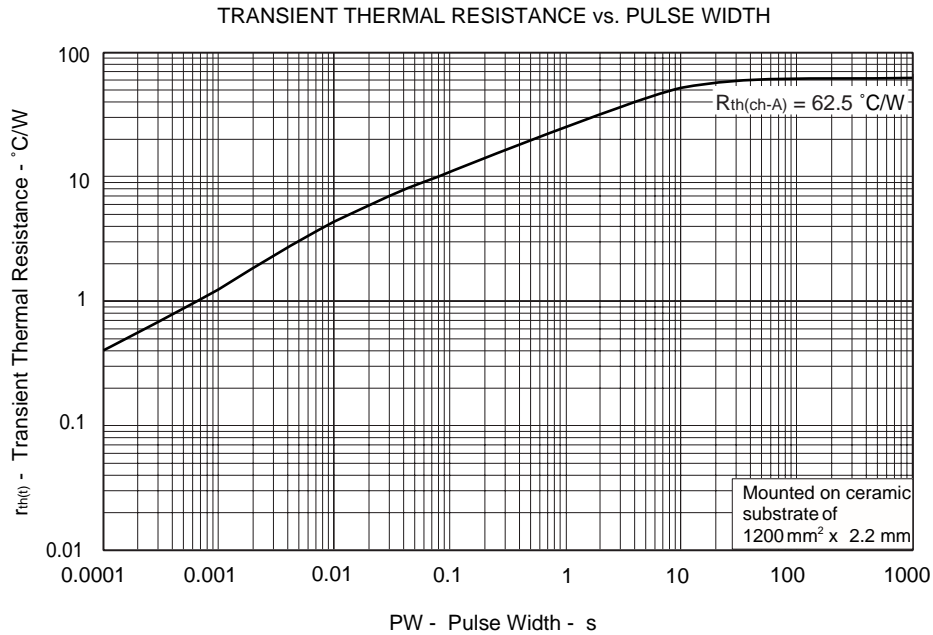
TEST CIRCUIT 2 GATE CHARGE

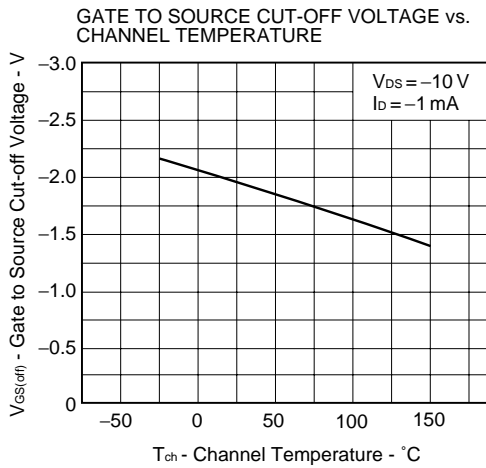
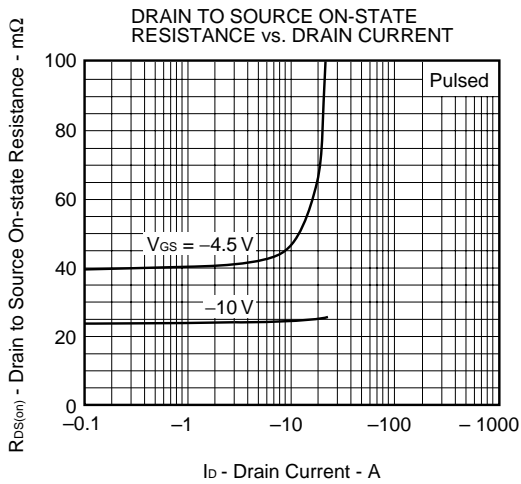
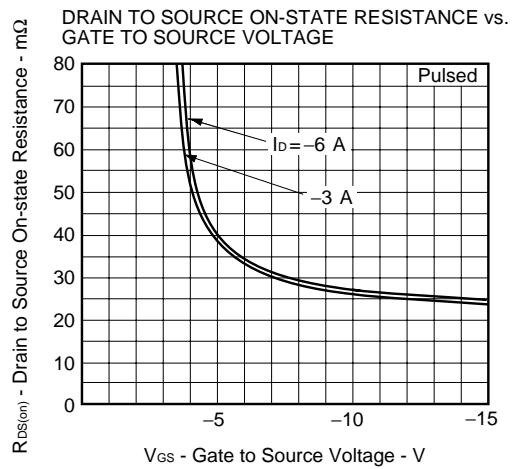
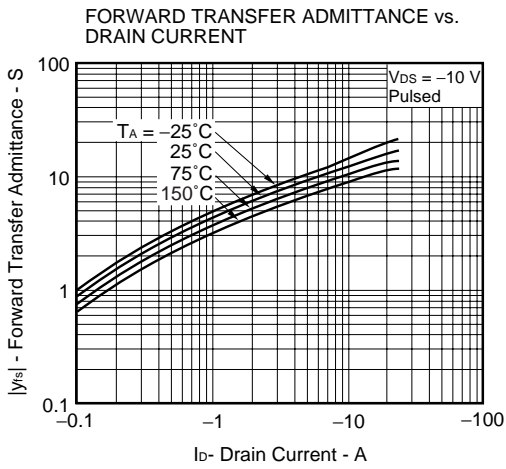
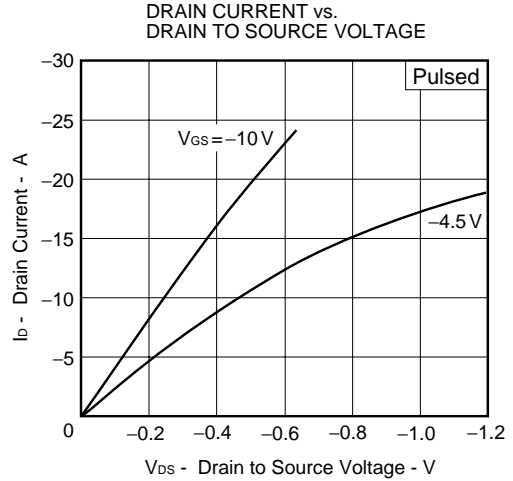
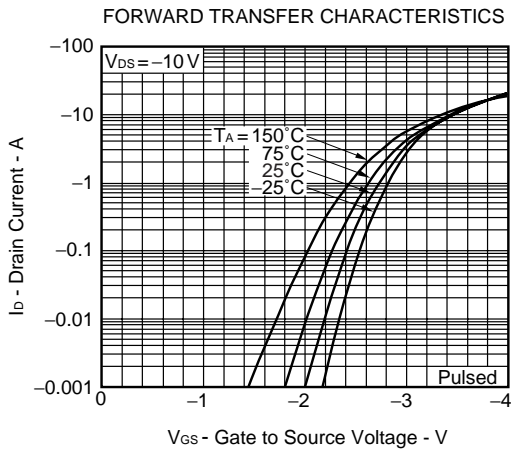


TYPICAL CHARACTERISTICS (T_A = 25 °C)

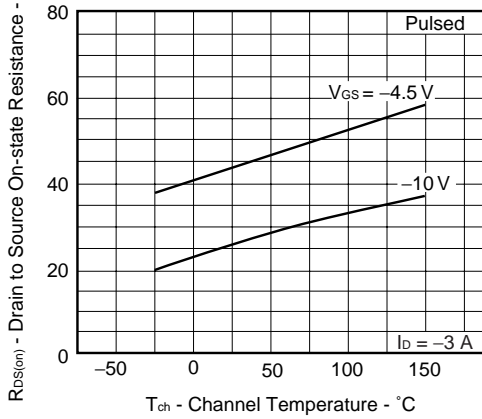


Remark Mounted on ceramic substrate of 1200 mm² x 2.2 mm

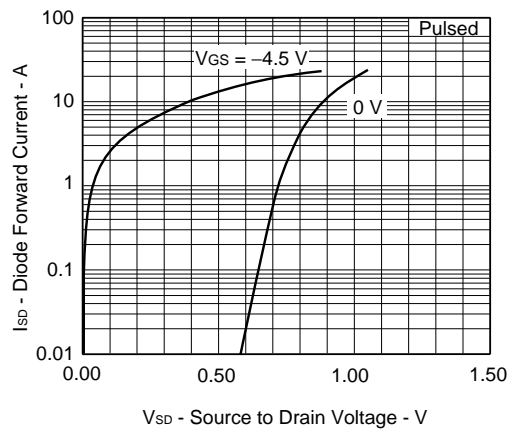




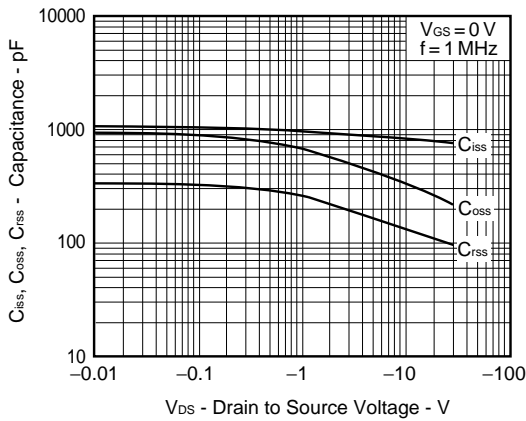
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



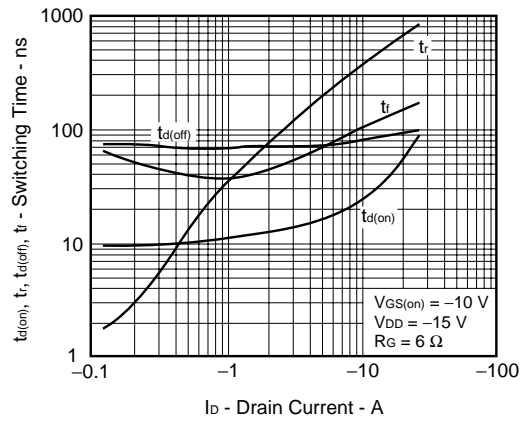
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



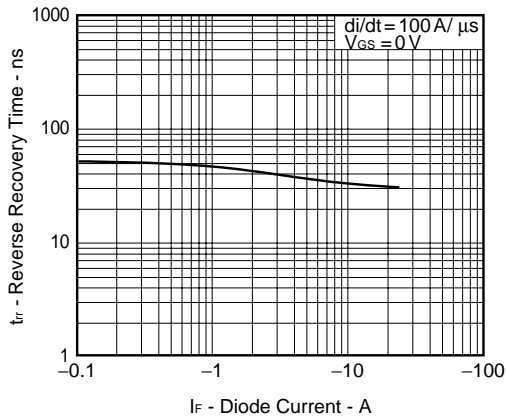
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



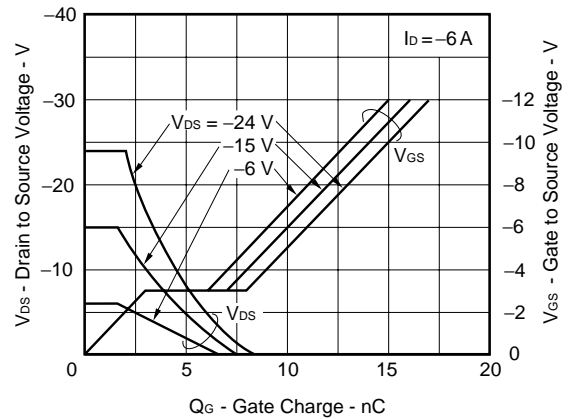
SWITCHING CHARACTERISTICS



REVERSE RECOVERY TIME vs. DIODE CURRENT



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



[MEMO]

[MEMO]

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